

Title (en)
DEVICE FOR TREATING SUBSTRATES

Title (de)
VORRICHTUNG ZUM BEHANDELN VON SUBSTRATEN

Title (fr)
DISPOSITIF POUR TRAITER DES SUBSTRATS

Publication
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Application
EP 00983207 A 20001202

Priority
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• EP 0012145 W 20001202

Abstract (en)
[origin: WO0146995A1] The aim of the invention is to provide a simple and economical device for opening and closing separate suction openings (13, 14, 15) of a device (1) which is provided for treating substrates, especially semiconductor wafers, and which comprises a treatment reservoir (3). Said treatment reservoir is filled with a treatment fluid and is arranged in an essentially closed space that has at least two separate suction openings (13, 14, 15). To this end, a rotatable disc (17) is provided which covers up the suction opening while isolating it from the space and which comprises a through-opening (18). One of the suction openings (13, 14, 15) can be at least partially overlapped by said through-opening.

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H01L 21/00

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